

# FIRST IN FIRST OUT BUFFER - SLC 20+



## SLC 20 +

With the FIFO (First-In-First-Out) buffers, 20-50 inner and outer layers can be buffered according to the chaotic warehouse management principle - be it to comply with downtimes of downstream processes or to maintain holding times after upstream processes. When an order management system is integrated, orders in the buffer can also be reprioritized. Via a lifting axle

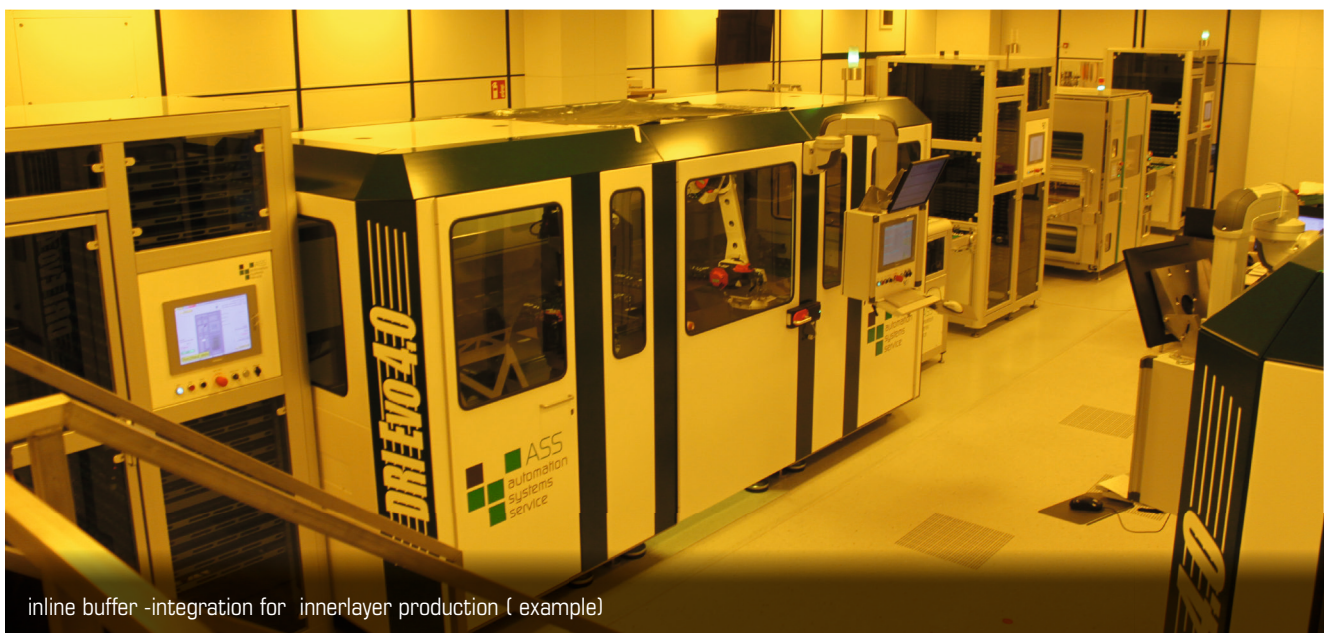
with transport device each floor of the buffer can be approached in any order. The buffer can be placed space-savings inline between processes, so that a continuous operation (without using the buffer) is possible without any additional space requirement. An optional integrated cooling extends the area of application of the buffer

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## HIGHLIGHTS

- Suitable for buffer solutions of single panel between any kind of processes
- Capacity loading and unloading max. 4 panels/min.
- Capacity: Basic version for 20 PCB/ substrates prepared for up to 50 PCB/ substrates
- Signal exchange to upstream and downstream process machines
- Data management per panel\*
- Multijob handling\*
- DMC reader and connection to MES as well as automatic order management\*
- Cooling by flow for each position\*

\*Optional



### Technical specifications

measurements (L/W/H)	1530 x 1350 x 2510 mm (2850 mit Ampel) mm	PCB format max.	610 x 610 mm
working hights	945 mm ± 50 mm	PCB thickness	0,05 - 4,5 mm